L Number		Search Text	DB	Time stamp
1	4963		USPAT	2004/05/12 16:1
,		Silver or Ag or gold or Au or aluminum or Al or nickel or Ni))		
2	725	The land ((wir\$ or cathode or electrode) same (copper or Cu or	USPAT	2004/05/12 16:1
		silver or Ag or gold or Au or aluminum or Al or nickel or Ni)		
	169	same laminat\$) ((light same emitting) same wiring) and 313/5 and		
	109	((light same emitting) same wiring) and 313/\$.ccls.	USPAT;	2003/07/30 17:3
			US-PGPUB;	
			EPO; JPO;	
	*)		DERWENT;	
	113	(((light same emitting) same wiring) and 313/\$.ccls.) and (film	IBM_TDB USPAT;	2002/04/45 00 5
		same (copper or Cu or silver or Ag or gold or Au or aluminum	US-PGPUB	2003/01/15 08:5
		or Al or nickel or Ni))	EPO; JPO;	
			DERWENT;	
	i		IBM_TDB	* * * * *
	72	(((light same emitting) same wiring) and 313/\$.ccls.) and	USPAT;	2003/01/15 08:5
		(Wiring same (copper or Cu or silver or Ag or gold or Au or	US-PGPUB:	
		aluminum or Al or nickel or Ni))	EPO; JPO;	190
			DERWENT;	***
		7/19:14	IBM_TDB	
	4	(((light same emitting) same wiring) and 313/\$.ccls.) and (via	USPAT;	2003/01/15 10:3
		adj hole)	US-PGPUB:	1
			EPO; JPO;	
			DERWENT;	+ , v , + + + + + + + + + + + + + + + +
	299	(313/500).CCLS.	IBM_TDB	
	299	(010/000):0008.	USPAT;	2003/01/15 10:3
			US-PGPUB;	
			EPO; JPO;	***
w i.	v. (*)		DERWENT;	8 4
	2919	(313/500-512) CCLS.	IBM_TDB	
1 3 1	2010	(5.0.000 012).0010.	USPAT;	2003/01/15 10:3
7	* * * * * * * * * * * * * * * * * * * *		US-PGPUB;	
			EPO; JPO; DERWENT;	1, 1,
			IBM_TDB	3.5
	96	((313/500-512) CCLS.) and (((light same emitting) same	USPAT;	2003/01/15 10:4
		wiring) and 313/\$.ccls.)	US-PGPUB;	2003/01/13 10:4
			EPO; JPO;	
20			DERWENT	
	·	71004 00 00 00 00 00 00 00 00 00 00 00 00	IBM_TDB	
	5	("3219865"). PN	USPAT;	2003/07/30 17:3
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	*
7.	1	("3219865").PN	IBM_TDB	
	6	(3219865").PN.) and wir\$	USPAT	2003/07/30 17:3
		((OZ 18000). FIN.) allu WIFD	USPAT;	2003/07/30 17:33
			US-PGPUB;	0.00
*	*		EPO; JPO;	
			DERWENT;	
4 . 7 7	1	3219865.pn. and wir\$	IBM_TDB	2002/27/22
:	210	((light same emitting) same wiring) and 313/\$.ccls.	USOCR	2003/07/30 17:33
		σ τοι τοι τοι τοι τοι στοι στοι στοι στ	USPAT; US-PGPUB;	2003/07/30 17:34
			EPO; JPO;	
			DERWENT:	
. 4			IBM_TDB	
	147	(((light same emitting) same wiring) and 313/\$.ccls.) and (wir\$	USPAT;	2003/07/30 17:50
	· · · · · · · · · · · · · · · · · · ·	same substrate)	US-PGPUB;	_000/01/30 17.30
			EPO; JPO;	
			DERWENT:	
		The first term of the first of	IBM_TDB	THE RESERVE OF
1	1	09/732049	USPAT,	2003/07/30 17:50
			US-PGPUB:	
٠.			EPO; JPO:	
8,	*		EPO; JPO; DERWENT;	- , ,

	1 .				
	-	1	09/732049 and wiring	USPAT;	2003/07/30 17:52
				US-PGPUB;	
		-	*	EPO; JPO;	
				DERWENT,	,
				IBM_TDB	
	- · · · · · · · · · · · · · · · · · · ·	33900	(printed adj wiring adj board) or PWB	USPAT;	2003/07/30 17:53
				US-PGPUB;	0.
				EPO; JPO;	
				DERWENT;	
		62	((printed adj wiring adj board) or PWB) and 313/\$.ccls.	IBM_TDB USPAT;	2000/07/00 47-50
		. 02	(Similed day willing adj board) of 1 VVD) and 515/\$.ccis.	US-PGPUB;	2003/07/30 17:53
٠.	100			EPO; JPO;	
-	-)()ic		A = 2	DERWENT:	
				IBM_TDB	
	•	26	((printed adj wiring adj board) or PWB) and 313/\$.ccls.	USPAT	2003/07/30 17:53
	÷	1 504	("5435937").PN.	USPAT	2003/07/31 08:40
•	-	531	(313/509).CCLS.	USPAT	2003/08/01 14:13
		736	substrate same wir\$ same phosphor	USPAT;	2003/07/31 08:54
		* . *		US-PGPUB;	
5		*		EPO; JPO; DERWENT;	
	1 2			IBM_TDB	
	<u>.</u>	108	(substrate same wir\$ same phosphor) and 313/\$.ccls.	USPAT	2003/07/31 08:55
	-	62	(substrate same wir\$ same phosphor same connect\$) and	USPAT	2003/07/31 08:59
			313/\$.ccls.		
	- '.	2	("3571647").PN.	USPAT;	2003/07/31 08:57
•				US-PGPUB;	
				EPO; JPO;	
				DERWENT; IBM_TDB	
		9	(substrate same wir\$ same phosphor same connect\$ same	USPAT	2003/07/31 09:32
			parallel) and 313/\$.ccls.	00.70	2000/01/01 05:52
	÷ ,	5331	(substrate same wir\$ same resin)	USPAT	2003/08/01 11:59
	· · · ·	178	(substrate same wir\$ same resin) and (light-emitting)	USPAT	2003/08/01 12:01
	-	4	(substrate same wir\$ same resin same (via with hole)) and	USPAT	2003/08/01 12:01
ı		363	(light-emitting)	LIODAT	
		303	(substrate same (electrode or wir\$) same (via adj hole) same resin)	USPAT; US-PGPUB;	2003/08/01 13:54
-		2.3.5		EPO; JPO;	
ı				DERWENT;	
	*	()		IBM_TDB	- 0
		3	(substrate same (electrode or wir\$) same (via adj hole) same	USPAT;	2003/08/01 14:02
1			resin same (lumin\$ or phosphor\$ or fluores\$))	US-PGPUB;	
				EPO; JPO;	
	*			DERWENT;	* * *
ĺ	· · · · · · · · · · · · · · · · · · ·	34	(substrate same (electrode or wir\$) same (via adj hole) same	IBM_TDB USPAT;	2003/08/01 14:12
			(lumin\$ or phosphor\$ or fluores\$))	US-PGPUB;	2000/00/01 14.12
				EPO; JPO;	
		0		DERWENT;	
		26793879	ID WOOLOOLEON A	IBM_TDB	
		20/938/9	JP "08139458" A	USPAT;	2003/08/01 14:13
ı		-		US-PGPUB;	
-				EPO; JPO; DERWENT;	
ĺ				IBM_TDB	
	-	531	(313/509).CCLS.	USPAT	2003/08/01 14:15
	-	114	((313/509).CCLS.) and via	USPAT	2003/08/01 14:24
	·	1	("4340840").PN.	USPAT	2003/08/01 14:30
	-	0 10	(gate adj control\$ adj wiring) and 313/\$.ccls.	USPAT	2003/08/01 14:32
٠	. y	7059	(gate with control\$ with wiring) and 313/\$.ccls.	USPAT	2003/08/01 14:32
			CASCULATE MICH MICH I COM	USPAT; US-PGPUB;	2003/08/19 19:16
		ľ		EPO; JPO;	*
		0	*	DERWENT;	
L			<u> </u>	IBM_TDB	

	<u> </u>				
	-	7456	substrate with fill\$ with resin	USPAT;	2003/08/19 19:16
				US-PGPUB:	2000/00/10 10:10
		· ·	. "	EPO; JPO;	
				DERWENT;	
			7 1	IBM_TDB	
- [-	0	The same with the state of the same same same same same same same sam	USPAT	2003/08/19 19:17
		23		USPAT	2003/08/21 08:40
İ	-	0 54	The same of the same (gate with control) same (date with anxillary)	USPAT	2003/08/19 19:30
		0	The same of the same (and the same same same will all same)	USPAT	2003/08/19 19:30
-			(substrate same (gate with control) same (gate with auxiliary)) and resin	USPAT	2003/08/19 19:31
		192		1,	
		27	((gate with control\$ with wiring) and clock) and resin	USPAT	2003/08/21 06:26
1			"09732049"	USPAT	2003/08/21 06:28
	-	1	("3219865").PN.	US-PGPUB	2003/08/21 06:36
	<u> -</u>	3	(substrate with fill\$ with resin) and 315/\$.ccls.	USPAT	2003/08/21 06:36
	-	1224	(313/495-497).CCLS.	USPAT	2003/08/21 07:29
1	• •	220	((313/495-497).CCLS.) and (layer\$ with wir\$)	USPAT;	2003/08/21 08:40 2003/08/21 08:54
1			(2)	US-PGPUB;	2003/06/21 08:54
				EPO; JPO;	
		1		DERWENT:	
	٠, . ٢			IBM_TDB	
	-	. 35	(((313/495-497) CCLS.) and (layer\$ with wir\$)) and resin	USPAT;	2003/08/21 09:16
	* .			US-PGPUB;	
				EPO; JPO;	
ĺ		**		DERWENT;	
	_		5702425 mg 2ml 2ml	IBM_TDB	1 1 1 1 1 1 1 1 1 1 1 1
l		0	5703435.pn. and gate	USPAT	2003/08/21 09:15
ľ		0	(((313/495-497) CCLS.) and (layer\$ with wir\$)) and (spacer	USPAT;	2003/08/21 09:21
			same resin)	US-PGPUB;	4.
		1 1 1		EPO; JPO;	
١.				DERWENT;	
Į.	- **	21	07/851701	IBM_TDB	
				USPAT;	2003/08/21 09:21
		* *		US-PGPUB;	10 0 g 4
	111 A	000		EPO; JPO; DERWENT;	
				IBM_TDB	
	÷ .	0	07/851701.ap.	USPAT	2003/08/21 09:21
١.	-	0	"07/851701".ap.	USPAT	2003/08/21 09:22
		21	07/851701	USPAT	2003/08/21 09:22
	•	536	(313/509).CCLS.	USPAT	2003/08/21 10:08
•	•	3	((313/509).CCLS.) and (via adj hole)	USPAT;	2003/08/21 10:08
				US-PGPUB;	
			•	EPO; JPO;	
				DERWENT;	
	- ()	1224	(313/495-497) CCLS.	IBM_TDB	
<u>:</u>		5	((313/495-497).CCLS.) and (via adj hole)	USPAT	2003/08/21 10:09
	. * •		(via auj liule)	USPAT;	2003/08/21 10:12
		*		US-PGPUB;	* * *
				EPO; JPO; DERWENT;	
	-	*		IBM_TDB	
1		18835	via adj hole	USPAT;	2003/08/21 10:12
				US-PGPUB;	2003/06/21 10:12
				EPO; JPO;	
				DERWENT:	4
		40005	And the second second	IBM_TDB	, 1
		18835	via adj hole	USPAT:	2003/08/21 10:12
-	1			US-PGPUB;	
-			* 10	EPO; JPO;	1
-	*	0.00			
-				DERWENT;	
_	Process of the second	7802	via adi holo	IBM_TDB	er in a var er
	Andrew W. Toronto	7802 2492	via adj hole	IBM_TDB USPAT	2003/08/21 10:12
	her A Two	2492	(via adj hole) same substrate	IBM_TDB USPAT USPAT	2003/08/21 10:13
	And A Took	2492 690	(via adj hole) same substrate ((via adj hole) same substrate) and resin	IBM_TDB USPAT USPAT USPAT	2003/08/21 10:13 2003/08/21 10:13
	And A loos	2492 690 19	(via adj hole) same substrate	IBM_TDB USPAT USPAT	2003/08/21 10:13

				•	
Ė	•	1	("5965981").PN.	LUODAT	T 0000 100 100 00 00
		4.5		USPAT	2003/08/22 08:33
	-	15	(((via adj hole) same substrate) and resin) and (EL or	USPAT	2003/08/22 09:54
-			electroluminescent) and wir\$		
		220	substrate same (EL or electroluminescent) same wir\$	USPAT	2003/08/22 09:55
- 1	-	84	substrate same (EL or electroluminescent) same wir\$ and	USPAT	
- 1			313/\$.ccls.	USPAT	2003/08/22.09:55
					· ·
	-	0	"09/732049" and 18A	US-PGPUB	2004/05/04 15:01
• .	4	1	"09/732049" and "18"	US-PGPUB	2004/05/04 15:01
	_	447344	"09/732049" and Fig. "18"	US-PGPUB	2004/05/04 15:02
	_	0	"09/732049" and "Fig. 18"		
		Ö		US-PGPUB	2004/05/04 15:02
		1		US-PGPUB	2004/05/04 15:02
	.	0	"09/732049" and "Fig.18A"	US-PGPUB	2004/05/04 15:02
- 1	- , ·	0	"09/732049" and "Fig. 18A"	US-PGPUB	2004/05/04 15:02
١.		1	"09/732049"	US-PGPUB	2004/05/04 15:02
	<u>.</u>	1	"09/732049"	and the second second	
-		1	"09/732049" and "current supply line"	US-PGPUB	2004/05/06 07:52
٠,		1	100/700040	US-PGPUB	2004/05/06 07:54
	-	1 1	"09/732049" and via	US-PGPUB	2004/05/06 07:54
ı		0	"09/732049" and (via same TFT)	US-PGPUB	2004/05/06 08:13
٠	-	1	"09/732049" and "metallic film"	US-PGPUB	2004/05/06 08:13
	_	1 1	"09/732049" and "main component"		
1.	41	1	"09/732049" and auxiliary	US-PGPUB	2004/05/06 08:36
- [1		US-PGPUB	2004/05/06 08:36
- [-	1	"09/732049"	USPAT;	2004/05/06 11:07
··.	- 9			US-PGPUB;	
1	*	1		EPO; JPO;	
٠.					
4,	* * * * * * * * * * * * * * * * * * * *	1"		DERWENT;	
		1	100/7000 401 5 1 - 1-4	IBM_TDB	
- []	•		"09/732049" and gate	USPAT;	2004/05/06 11:09
	0			US-PGPUB;	0.0
1	• • •			EPO; JPO;	
				DERWENT:	
	*				
Ί.		4	"09/732049" and clock	IBM_TDB	
	9		U9/732U49 and clock	USPAT;	2004/05/06 11:10
				US-PGPUB:	
	3.75			EPO; JPO;	**
				DERWENT:	
1.		1	"09/732049" and "gate control wiring"	IBM_TDB	leri kasalu — I
	ere e		09/732049 and gate control wiring	USPAT;	2004/05/06 11:14
		4		US-PGPUB;	
				ÉPO; JPO;	
				DERWENT;	
				IBM TDB	
-		773	(313/500,505,498).CCLS.		000405050505
۔ ا			TFT and PWB	USPAT	2004/05/07 07:26
1			II I AIIU TVD	USPAT	2004/05/06 12:20
-		. 1	"6312836".PN	USPAT	2004/05/06 14:38
		773	(313/500,505,498).CCLS.	USPAT	2004/05/07 09:45
-		62	((313/500,505,498).CCLS.) and (TFT or thin\$film\$transistor)	USPAT	2004/05/07 07:52
-		1	("6215244").PN.	USPAT	100
_	7.1	1	(("6215244") PN.) and (copper or silver or gold or aluminum or		2004/05/07 07:52
1			nickel)	USPAT	2004/05/07 07:55
		1404			* .
-	*	1404	(conductive adj paste) with (copper or silver or gold or	USPAT	2004/05/07 07:55
		. "	aluminum or nickel)		
-		63	((conductive adj paste) with (copper or silver or gold or	LICDAT	2004/05/07 07:50
	- 90	-	aluminum or nickel)) and 313/\$.ccls.	USPAT	2004/05/07 07:56
1.	٠. ١	6	(Manadustica adia adia adia)		
] -		. 0	(((conductive adj paste) with (copper or silver or gold or	USPAT.	2004/05/07 07:56
1	· · · : 1		aluminum or nickel)) and 313/\$.ccls.) and TFT	;	
] -	. 1	773	(313/500,505,498).CCLS.	USPAT	2004/05/11 07:14
-	1	1905	(315/169.1,169.2,169.3).CCLS.	USPAT	2004/05/07 09:45
1 -	0 0	1792	((315/169.1,169.2,169.3).CCLS.) not		
	•	., 52		USPAT	2004/05/07 09:47
13		4-5	((313/500,505,498).CCLS.)	*	A6
.] =		153	(((315/169.1,169.2,169.3).CCLS.) not	USPAT	2004/05/07 09:47
	: · · · · · · · · · · · · · · · · · · ·	*	((313/500,505,498).CCLS.)) and (TFT or thin\$film\$transistor)		
		171	(((315/169.1,169.2,169.3).CCLS.) not	USPAT	2004/05/07 00:40
1.	e - 100 ·	ere ere de erecenti	((313/500,505,498).CCLS.)) and (TFT or thin\$film\$transistor)	USEA1	2004/05/07 09:48
1_		2451	(313/504 503 504 506 543) 001 (1 F 1 OF INHIQHIMATICANSISTOR)		
-	ľ		(313/501,502,503,504,506-512).CCLS.	USPAT	2004/05/11 07:14
-		775	(313/500,505,498) CCLS.	USPAT	2004/05/11 07:14
1 -	-]	2027	((313/501,502,503,504,506-512).CCLS.) not	USPAT	2004/05/11 07:15
1	i		((313/500,505,498).CCLS.)	-0.71	2007/00/11 07.15
			113 13/300.303.4901.GCE3.1		

	-				
	-	110	(((313/501,502,503,504,506-512).CCLS.) not	USPAT	2004/05/11 07:34
	-		((313/500,505,498).CCLS.)) and (TFT or thin\$film\$transistor)	001 71	2004/03/11 07.34
•		1077	(345/44,45,46,55,76).CCLS.	USPAT	2004/05/42 00:07
	_	919	((345/44,45,46,55,76).CCLS.) not		2004/05/12 09:07
		0.0	(((313/501,502,503,504,506-512).CCLS.) or	USPAT	2004/05/11 07:34
			(((313/500,505,498).CCLS.))		
	_	154		ا المالية	
		104	(((345/44,45,46,55,76).CCLS.) not	USPAT	2004/05/11 08:08
		4 1	(((313/501,502,503,504,506-512).CCLS.) or		
	x - 1		((313/500,505,498) CCLS.))) and (TFT or (thin\$ adj film\$ adj		1 .
	* * * .	4007	transistor\$))		
		1827	(257/99-103).CCLS.	USPAT	2004/05/11 08:08
		1539	((257/99-103).CCLS.) not	USPAT	2004/05/11 08:08
			(((313/501,502,503,504,506-512).CCLS.) or		
	*		((313/500,505,498).CCLS.) or ((345/44,45,46,55,76).CCLS.))	* 1	
		37	(((257/99-103).CCLS.) not	USPAT	2004/05/11 09:10
		**	(((313/501,502,503,504,506-512).CCLS.) or		
			((313/500,505,498).CCLS.) or ((345/44,45,46,55,76).CCLS.)))	* - 1	
			and (TFT or (thin\$ adj film\$ adj transistor\$))	* 100	0
	-	. 2	(("5990629") or ("6641933")).PN.	USPAT	2004/05/11 09:12
	, -	1	("6611108").PN.	USPAT	2004/05/11 09:13
	-	1	("6714268").PN.	USPAT	2004/05/11 09:15
		6976	yamazaki.in.	USPAT;	2004/05/11 09:15
				US-PGPUB	2004/00/11 03:15
Ì	·	1620	yamazaki.in.	US-PGPUB	2004/05/11 09:15
	- : '	560	yamazaki.in. and TFT	US-PGPUB	2004/05/11 09:53
ĺ	- ,	4108	349/\$.ccls. and TFT	USPAT	2004/05/11 18:14
		1	("5962959").PN.	USPAT	2004/05/11 18:14
	-	1	("5990629").PN	USPAT	2004/05/11 18:14
	- 1	7	("5193017" "5327268" "5408345" "5426526" "5777696"	USPAT	2004/05/12 08:30
-			"5786242" "5805252").PN.	USPAT	2004/05/12 09:01
1	*,	2027	((313/501,502,503,504,506-512).CCLS.) not	USPAT	2004/05/40 00:05
1		.,	((313/500,505,498).CCLS.)	USPAI	2004/05/12 09:05
1	_	28	(313/500,505,498).CCLS. and TFT and resin	LICDAT	00040544000
۱ ا	_	72	((313/501,502,503,504,506-512).CCLS.) and TFT and resin	USPAT	2004/05/12 09:04
	_	1077	(345/44,45,46,55,76).CCLS.	USPAT	2004/05/12 09:06
		40	((345/44,45,46,55,76).CCLS.) and TFT and resin	USPAT	2004/05/12 09:07
1	_ (7	- ((マエン/オセ,オセ,30;70).OCLO.) and TET.and resin - ("5103017" L "5327260" L "5300245" L "5400500" L "535500" L	USPAT	2004/05/12 09:15
1		'	("5193017" "5327268" "5408345" "5426526" "5777696"	USPAT	2004/05/12 09:11
	<u> </u>	4	"5786242" "5805252").PN.	l	
		1	5990629.pn. and resin	USPAT	2004/05/12 09:17
			5990629.pn. and EL	USPAT	2004/05/12 09:17
1			("6225966").PN.	USPAT	2004/05/12 09:17
L	·=	1	(("6225966").PN.) and EL	USPAT	2004/05/12 16:12